

JOB ORDER FORM

JOF ind. 2 fev. 2012

CUSTOMER				RESERVED FOR IE	BS
COMPANY*:				N°OF:	
CONTACT*:				IV UF.	
PHONE:				Cada	
FAX:				Code:	
EMAIL*:				RUSH service:	Yes No
P.O. #:				KUSH Sei VICE.	
Ship date :		Carrier:			
Tracking nb:					
SUBSTRATE				LOT IDENTIFICAT	ION
Material*:				Lot	Wafercount
Size*:					
Thickness*:					
Mask*:	Side to process:	☐ No mask	Oxide Photoresist		
	Opposite Side:	☐ No mask ☐ Metal	Oxide Photoresist		
Remarks:					
PROCESS PARAMETERS				N OF THE SIDE TO BE	
Type*: Oxidation Deposition Dry Etch	☐ Annealing ☐ Photolithograp ☐ Wet Etch	ohy	Polished Side With Numbers	With	Polished Side nout Numbers
Specification:			☐ With Structure	s	out Structures
Remarks:			1		



Engineer Name:

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INCOMING CONTROL						
Integrity of the parcel:	Yes	☐ No	Non-Con	formity Note:		
Conformity of documents:	Yes	☐ No	Non-Conformity Note:			Date: Visa:
CONTROL BEFORE DROCESS						visa.
CONTROL BEFORE PROCESS Processed side identifiable:	Yes	□ No				
Mask in compliance with paperwork:	Yes	□ No				
Wafercount in compliance with paperwork:	□ок	Non conf	form			
Condition of wafers:	Yes	☐ No				
Non-Conformity note:						
				Date:		Visa:
EQUIPMENT PARAMETERS						
Equipement:						
Recipe:						
Remarks:						
				Date:		Visa:
CONTROL DURING PROCESS						
Vacuum (if applicable):						
Integrity of substrate: (visual aspect after process)	ОК	Non conf	form			
Remarks:						_
				Date:		Visa:
CONTROL AFTER PROCESS						
Measurements Results:					ОК	Non conform
Checks/Inspection Results:					ок	☐ Non conform
Non-Conformity note:						
Attached documents						
Remarks:				Date:		Visa:

Date:

Visa: